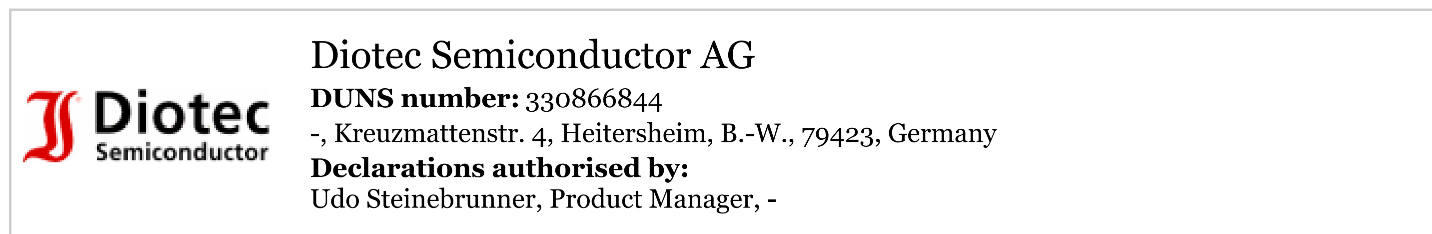
Full Material Declaration for attached parts list

Report generated: 25 February 2016, 14:03 GMT



Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 May 2009 [Approved on 25 February 2016, 14:02 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.20000%	Nickel	7440-02-0	0.90000%
			Gold	7440-57-5	10.30000%
			Polydimethyl siloxane	63148-62-9	25.30000%
			Silicon	7440-21-3	63.50000%
Die attach	Lead and Lead alloys	0.10000%	Silver	7440-22-4	1.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	93.50000%
Encapsulation	EP (Epoxy resin)	23.30000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			Tetrabromobisphenol A (TBBPA)	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Leadfinish	Tin plating	2.40000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	74.00000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
~DO-201	Diode axial	0.8	g